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1. (Amended) A method of manufacturing a display device,  
comprising:  
forming a peeling layer on a first substrate;  
forming an insulating layer on said peeling layer;  
forming a light emitting element on said insulating layer;  
bonding a second substrate over said light emitting element  
by using a first adhesive;  
exposing the peeling layer to a gas containing halogen  
fluoride after bonding said second substrate to thereby remove  
said peeling layer and the first substrate; and  
bonding a third substrate to said insulating layer by using  
a second adhesive.

2. (Amended) A method according to claim 1, wherein said  
first adhesive is selected from the group consisting of  
polyimide, acrylic, and epoxy resin.

3. (Amended) A method according to claim 1, wherein the  
third substrate comprises the same material as the second  
substrate.

4. (Amended) A method of manufacturing a display device,  
comprising:  
forming a peeling layer on a first substrate;

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forming an insulating layer on said peeling layer;  
forming a semiconductor element on said insulating layer;  
forming at least one interlayer insulating film over the  
semiconductor element;  
forming a light emitting element over the interlayer  
insulating film, the light emitting element electrically  
connected to said semiconductor element;  
bonding a second substrate over said light emitting element  
by using a first adhesive;  
A exposing the peeling layer to a gas containing halogen  
fluoride after bonding said second substrate to thereby remove  
said peeling layer and first substrate; and  
bonding a third substrate to said insulating layer by using  
a second adhesive.

5. (Amended) A method according to claim 4, wherein said  
first adhesive is selected from the group consisting of  
polyimide, acrylic, and epoxy resin.

6. (Amended) A method according to claim 4, wherein the  
third substrate comprises the same material as the second  
substrate.

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Please add the following new claims 16-43.

Sub B7 16. A method according to claim 1, wherein the first substrate is selected from the group consisting of glass, quartz, silicon, metal, and ceramic substrates.

17. A method according to claim 1, wherein the second substrate is selected from the group consisting of plastic, glass, quartz, silicon, metal, and ceramic substrates.

18. A method according to claim 1, wherein the peeling layer comprises silicon.

19. A method according to claim 1, wherein the insulating layer comprises silicon and oxygen.

20. A method according to claim 1, further comprising a step of forming openings in the insulating layer before said exposing.

21. A method according to claim 4, wherein the first substrate is selected from the group consisting of glass, quartz, silicon, metal, and ceramic substrates.

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22. A method according to claim 4, wherein the second substrate is selected from the group consisting of plastic, glass, quartz, silicon, metal, and ceramic substrates.

23. A method according to claim 4, wherein the peeling layer comprises silicon.

24. A method according to claim 4, wherein the insulating layer comprises silicon and oxygen.

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25. A method according to claim 4, further comprising a step of forming openings in the insulating layer and the interlayer insulating film before said exposing.

26. A method of manufacturing a display device, comprising:  
forming a peeling layer on a first substrate;  
forming an insulating layer on the peeling layer;  
forming a switching element on the insulating layer;  
forming at least one interlayer insulating film over the switching element;

forming a display element over the interlayer insulating film, the display element electrically connected to the semiconductor element;

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bonding a second substrate over the display element by  
using a first adhesive;

exposing the peeling layer to a gas containing halogen  
fluoride after bonding the second substrate to thereby remove  
the peeling layer and the first substrate; and

bonding a third substrate to the insulating layer by using  
a second adhesive.

27. A method according to claim 26, wherein the first  
substrate is selected from the group consisting of glass,  
quartz, silicon, metal, and ceramic substrates.

28. A method according to claim 26, wherein the second  
substrate is selected from the group consisting of plastic,  
glass, quartz, silicon, metal, and ceramic substrates.

29. A method according to claim 26, wherein the third  
substrate comprises the same material as the second substrate.

30. A method according to claim 26, wherein said first  
adhesive is selected from the group consisting of polyimide,  
acrylic, and epoxy resin.

31. A method according to claim 26, wherein the display device is a liquid crystal display device.

32. A method according to claim 26, wherein the display device is an electroluminescence display device.

33. A method according to claim 26, wherein the peeling layer comprises silicon.

34. A method according to claim 26, wherein the insulating layer comprises silicon and oxygen.

35. A method according to claim 26, further comprising a step of forming openings in the insulating layer and the interlayer insulating film before said exposing.

36. A method of manufacturing a display device comprising:  
forming a peeling layer on a first substrate;  
forming an insulating layer on the peeling layer;  
forming active layers, a gate insulating layer, and gate electrodes over the insulating layer;  
forming a first interlayer insulating layer to cover the gate electrodes;

Sub B17 forming wirings and pixel electrodes over the first interlayer insulating layer, the wirings and the pixel electrodes electrically connected with the active layers, respectively;

exposing the peeling layer to a gas containing halogen fluoride to thereby remove the peeling layer;

forming a light emitting layer and a cathode on the pixel electrode;

bonding a second substrate on the cathode by using a first adhesive;

removing the first substrate after bonding the second substrate; and

bonding a third substrate to the insulating layer by using a second adhesive.

37. A method according to claim 36, wherein the first substrate is selected from the group consisting of glass, quartz, silicon, metal, and ceramic substrates.

38. A method according to claim 36, wherein the second substrate is selected from the group consisting of plastic, glass, quartz, silicon, metal, and ceramic substrates.

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39. A method according to claim 36, wherein the third substrate comprises the same material as the second substrate.

40. A method according to claim 36, wherein said first adhesive is selected from the group consisting of polyimide, acrylic, and epoxy resin.

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41. A method according to claim 36, wherein the peeling layer comprises silicon.

42. A method according to claim 36, wherein the insulating layer comprises silicon and oxygen.

43. A method according to claim 36, further comprising a step of forming openings in the insulating layer and the interlayer insulating film before said exposing.